



Material Content Data Sheet



Sales Product Name		TLD5098EL		Issued		28. August 2013		
MA#		MA000982098						
Package		PG-SSOP-14-3		Weight*		83.26 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.131	2.56	2.56	25601	25601
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		103	
	non noble metal	zinc	7440-66-6	0.034	0.04		414	
	non noble metal	iron	7439-89-6	0.689	0.83		8276	
wire	non noble metal	copper	7440-50-8	27.978	33.60	34.48	336046	344839
	noble metal	gold	7440-57-5	0.395	0.47	0.47	4739	4739
	encapsulation	organic material	carbon black	1333-86-4	0.099	0.12		1190
plastics	plastics	epoxy resin	-	4.558	5.48		54752	
		silicondioxide	60676-86-0	44.890	53.92	59.52	539186	595128
leadfinish	non noble metal	tin	7440-31-5	0.976	1.17	1.17	11724	11724
plating	noble metal	silver	7440-22-4	0.768	0.92	0.92	9220	9220
glue	plastics	epoxy resin	-	0.182	0.22		2187	
		noble metal	silver	7440-22-4	0.546	0.66	0.88	6562
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com